

Class KC equivalent die up-screening

MIL-PRF-19500 JANKC Equivalent Up-Screening Rev. R		
Screening Requirements		
Test	Quantity (Accept Number of Failures)	MIL-STD-750
Subgroup 1: Electrical Test	100%	As per Electrical Datasheet
Subgroup 2: Visual Inspection	100%	2069, 2070, 2072, 2073
Subgroup 3A: Internal/Die Visual Inspection	22 devices per wafer (0)	2069, 2070, 2072, 2073
Subgroup 3B: Sample Assembly	22 devices per wafer (0)	
Subgroup 4A: Temperature Cycling	22 devices per wafer (0)	1051-C, 20 Cycles
Subgroup 4B: Mechanical Shock or Constant Acceleration	22 devices per wafer (0)	2016 or 2006 Y1 Axis Direction
Subgroup 4C: Electrical Test: DC Test @ 25°C / DC Test @ TA MIN / DC Test @ TA MAX/ AC Test @ 25°C (DC2-DC4) (AC1) AC Test are performed when applicable	22 devices per wafer (0)	As per Electrical Datasheet
Subgroup 4D: HTRB	22 devices per wafer (0)	1038-A, 1039-A, 1042-B, 48 Hours (PNP 24 Hours), 80% Rated V_R , $T_A = 150^\circ\text{C}$
Subgroup 4E: Electrical Test (DC5)	22 devices per wafer (0)	As per Electrical Datasheet
Subgroup 4F: Burn-In	22 devices per wafer (0)	1038-B, 1039-B, 1042-A, 160 Hours (Diode 96 Hours), $T_J = \text{Max Junction}$ Temperature
Subgroup 4G: Electrical Test: DC Test @ 25°C (DC6)	22 devices per wafer (0)	As per Electrical Datasheet
Subgroup 4H: Steady State Life	22 devices per wafer (0)	1038-B, 1039-B, 1042-A, 160 Hours (Diode 96 Hours), $T_J = \text{Max Junction}$ Temperature
Subgroup 4I: Electrical Test: DC Test @ 25°C / DC Test @ TA MIN / DC Test @ TA MAX / AC Test @ 25°C (DC7-DC9)	22 devices per wafer (0)	As per Electrical Datasheet
Subgroup 5A: Wire Pull	10 Wires (0) or 20 Wires (1)	2037, 1 Hour 300°C Pre- Test Bake (Bimetallic Bonds only)
Subgroup 5B: Die Shear	5(0) or 10 (1)	2017



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Subgroup 6: SEM	Per Mil Standard	2077
Subgroup 7A: RHA Total Dose	As per customer requirement	1019
Subgroup 7B: Neutron Irradiation	As per customer requirement	1017

Note: Devices supplied will be to the test flow illustrated above. Any changes to the flow must be agreed upon in writing by the customer and Central Semiconductor Corp.